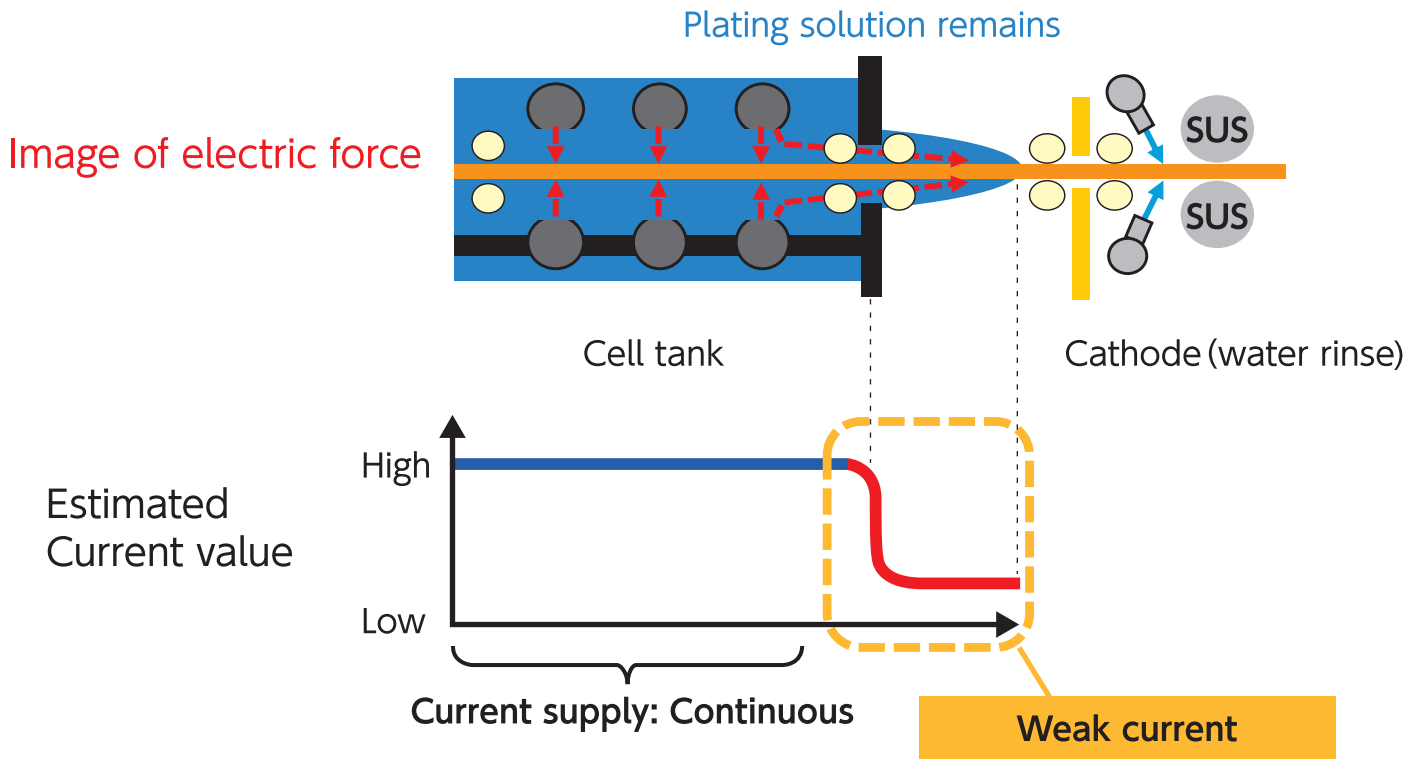


Acid copper plating additive for horizontal Roll to Roll plating

TOP LUCINA SVP

- Realize via-filling plating by horizontal plating equipment
- Reduce the impact by weak current
- Great via-filling and throwing power performance (Patented)



Realize full filling for horizontal Roll to Roll equipment

	TOP LUCINA SVP	Conventional
Filling performance Via diameter 75 μm Via depth 36 μm		
Throwing power Diameter 100 μm		

Plating condition (6 A/dm², 30 s) \Leftrightarrow (0.2 A/dm², 5 s)

Surface thickness 12 μm

New equipment: Horizontal Roll to Roll plating equipment in our factory (Osaka)

Can treat Flexible Copper Clad Laminates
with 250 mm width

By prototype test in our pilot line, we find the best
chemicals and processes for you.

